

Customer Inquiry Sputter Requirements Survey

Please provide as much information as possible in the following survey and email it to sales@allwin21.com / allwin21corp@gmail.com. The more complete and accurate your responses, the better we can recommend the most suitable Sputtering Deposition system model or configuration for your specific needs, based on our 45 years of Sputtering Deposition experience and hundreds of successful installation worldwide. Completing the survey thoroughly will ensure optimal system performance while avoiding unnecessary options that do not contribute to your application. We greatly appreciate your time and effort.

Section 1: Contact Information

- (1) Full Name:
- (2) Email Address:
- (3) Company Name:
- (4) Company Address:
- (5) Phone Number (Option):

Section 2: Sputtering Deposition System Requirements

- (1) Type of Sputtering Deposition System Required:
 Semi-Automatic Batch; Fully Automatic Batch Wafer; Others:
 DC Magnetron; RF Magnetron; RF Diode; Pulse DC Magnetron; Others:
- (2) Substrate Size (Small Pieces, 1", 2", 3", 4", 5", 6", 8", Others) :
- (3) Substrate Material (Si, GaAs, GaN, SiC, InP, GaInP, AlN, Quartz, Others) :
- (4) Sputtering Materials:
 Ag; Al; Al₂O₃; Au; Cr; CrNx; CrSi₂; Cu; Mo; MoSi₂; Ni; Nichrome; Pd; Permalloy; Pt;
 Quartz; Si; Si₃N₄; Ta; TaNx; Ti; TiNx; Ti/W(10%); W; WNx; Others:
- (5) Cathode Type and Amount: 8 inch -1; 8 inch -2; 8 inch -3; 8 inch -4;
 Delta -1; Delta -2; Delta -3; Others:
- (6) Maximum Power Supply Watts for sputtering:
DC Power: _____ ; Pulse DC Power: _____ ; RF Generator: _____
- (7) Process Gases: Ar -100SCCM MFC; Ar -200 SCCM MFC; O₂ -100 SCCM MFC; N₂ -100 SCCM MFC;
 N₂ -10 SCCM MFC; Others with MFC flow rate: _____
- (8) Plasma Clean/Etch Function: Yes; No. If yes, maximum RF Power supply watts: _____
- (9) Loadlock IR Lamp Heating Function: Yes; No.
- (10) Chamber IR Lamp Heating Function: Yes; No.
- (11) Turbo Pump for loadlock: Yes; No.
- (12) Co-Sputter Function: Yes; No.
- (13) Reactive Sputter Function: Yes; No. If Yes, (a) What kind of target for reactive sputtering process? (b) What is the repeatability and uniformity? (c) Use RF sputtering or DC sputtering? (d) What kind of reactive gas to be used? N₂ or O₂, or both, or both but at different separated steps? (e) Do you have any current process for your reactive sputtering? If yes, what kind of condition (gas flow, pressure and power) if you can provide: _____
- (14) RF Bias function: Yes; No.
- (15) Chamber high vacuum pump type: Turbo Pump; Cryo Pump.

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(16) Network / automation functions such as EAP, GEM/SECS: Yes; No; Others:

Section 3: Previous Experience & Brand Awareness

- (1) Have you previously used any sputtering deposition system that met your requirements? If yes, please specify brand and model:

- (2) Are you familiar with Perkin-Elmer sputtering deposition systems? If yes, please specify the model(s):

Section 4: Project & Procurement Information

- (1) Approximate Budget:
- (2) Estimated Purchase Timeline:
- (3) Throughput Requirements (e.g., wafers/hour/Day/Week/Month/Year):
- (4) Application Background and Other Special Requirements: